

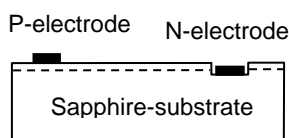
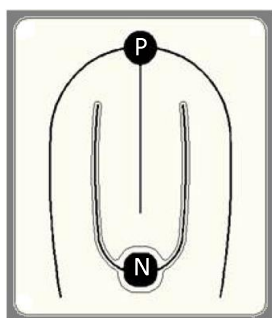
### > Mechanical Specification:

#### (1) Dimension

- Chip size: 26 mil x 30 mil ( $650 \pm 25 \mu\text{m} \times 750 \pm 25 \mu\text{m}$ )
- Thickness: 7.9 mil ( $200 \pm 10 \mu\text{m}$ )
- P bonding pad: 3.1 mil ( $80 \pm 10 \mu\text{m}$ )
- N bonding pad: 3.1 mil ( $80 \pm 10 \mu\text{m}$ )

#### (2) Metallization

- Topside P electrode: Au alloy
- Topside N electrode: Au alloy



#### Features:

- High radiant flux
- Long operation life
- Lambertian radiation
- High anti-ESD level

#### Applications:

- Lighting
- Backlight

### > Electro-optical Characteristics at 25°C: <sup>(1)</sup>

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	
Forward Voltage	Vf1	If = 10μA	1.6	-	-	V	
	Vf2	If = 120mA	-	3.0	3.2	V	
Reverse Current	Ir	Vr = 5V	-	-	2.0	μA	
Dominant Wavelength <sup>(2)</sup>	λd	If = 120mA	445	-	465	nm	
Spectra Half-width	Δλ	If = 120mA	-	25	-	nm	
Radiant Flux <sup>(3)(4)</sup>	Po	A72	If = 120mA	230	-	240	mW
		A73		240	-	250	
		A74		250	-	260	

Note:

(1) ESD protection during chip handling is recommended.

(2) Basically, the wavelength span is 20nm; however, customers' special requirements are also welcome.

(3) Radiant flux is determined by using an Ag-plated TO-can header without an encapsulant.

(4) Radiant flux measurement allows a tolerance of ±15%.

## > Absolute Maximum Ratings:

Parameter	Symbol	Condition	Rating	Unit
Forward DC Current	If	Ta = 25°C	≤ 240	mA
Reverse Voltage	Vr	Ta = 25°C	≤ 5	V
Junction Temperature	Tj	-	≤ 125	°C
Storage Temperature	Tstg	Chip	-40 ~ +85	°C
		Chip-on-tape/storage	5 ~ 35	°C
		Chip-on-tape/transportation	-20 ~ +65	°C
Temperature during Packaging	-	-	280(<10sec)	°C

Note: Maximum ratings are package dependent. The above maximum ratings were determined using a Metal Core Printed Circuit Board (MCPCB) without an encapsulant. Stresses in excess of the absolute maximum ratings such as forward current and junction temperature may cause damage to the LED.

## > Characteristic Curves:

Fig.1 – Relative luminous Intensity vs. Forward Current

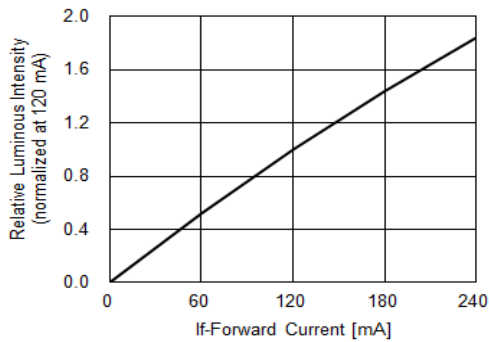


Fig.2 – Forward Current vs. Forward Voltage

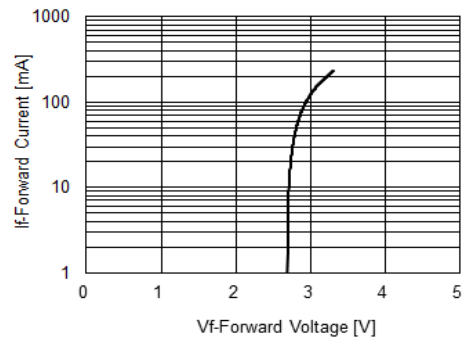


Fig.3 – Relative Intensity (@120mA) vs. Ambient Temperature

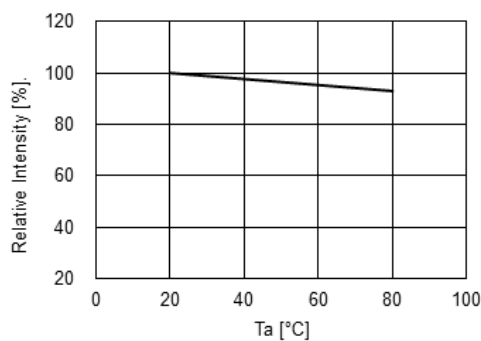


Fig.4 – Forward Voltage (@120mA) vs. Ambient Temperature

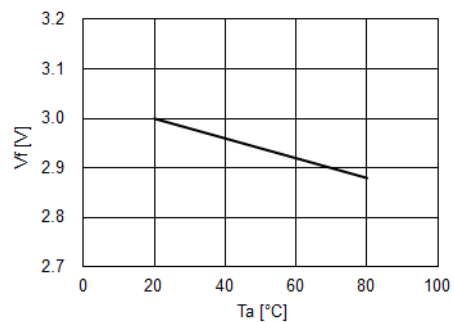


Fig.5 – Dominant Wavelength (@120mA) vs. Ambient Temperature

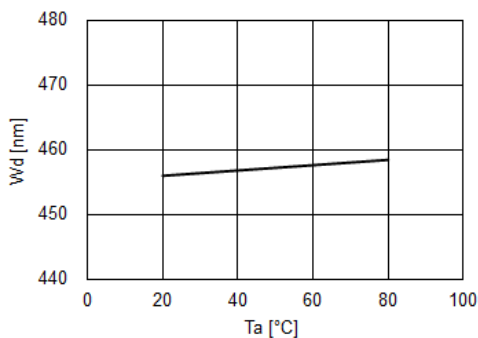


Fig.6 – Maximum Driving Forward DC Current vs. Ambient Temperature (De-rating based on Tj max. = 125°C)

